

Intel® Core™ i3-370M Processor

3M cache, 2.40 GHz

Specifications

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Essentials

Product Collection	Legacy Intel® Core™ Processor
Code Name	Products formerly Arrandale
Vertical Segment	Mobile
Processor Number	i3-370M
Status	End of Interactive Support
Launch Date	Q3'10
Lithography	32 nm
Recommended Customer Price	N/A

Performance

# of Cores	2
# of Threads	4
Processor Base Frequency	2.40 GHz
Cache	3 MB SmartCache
Bus Speed	2.5 GT/s DMI
TDP	35 W

Supplemental Information

Embedded Options Available	No
Datasheet	View now

Memory Specifications

Max Memory Size (dependent on memory type)	8 GB
Memory Types	DDR3 800/1066

Max # of Memory Channels	2
Max Memory Bandwidth	17.1 GB/s
Physical Address Extensions	36-bit
ECC Memory Supported ‡	No

Graphics Specifications

Processor Graphics ‡	Intel® HD Graphics
Graphics Base Frequency	500 MHz
Graphics Max Dynamic Frequency	667 MHz
Intel® Flexible Display Interface (Intel® FDI)	Yes
Intel® Clear Video HD Technology	Yes
Intel® Clear Video Technology	Yes
Macrovision* License Required	No
# of Displays Supported ‡	2

Expansion Options

PCI Express Revision	2.0
PCI Express Configurations ‡	1x16
Max # of PCI Express Lanes	16

Package Specifications

Sockets Supported	PGA988
Max CPU Configuration	1
T _{JUNCTION}	90°C for rPGA, 105°C for BGA
Package Size	rPGA 37.5mmx 37.5mm, BGA 34mmx28mm
Processing Die Size	81 mm ²
# of Processing Die Transistors	382 million
Low Halogen Options Available	See MDDS

Advanced Technologies

Intel® Turbo Boost Technology ‡	No
Intel® vPro™ Technology ‡	No
Intel® Hyper-Threading Technology ‡	Yes
Intel® Virtualization Technology (VT-x) ‡	Yes

Intel® Virtualization Technology for Directed I/O (VT-d) ‡	No
Intel® VT-x with Extended Page Tables (EPT) ‡	Yes
Intel® 64 ‡	Yes
Instruction Set	64-bit
Instruction Set Extensions	SSE4.1/4.2
Idle States	Yes
Enhanced Intel SpeedStep® Technology	Yes
Thermal Monitoring Technologies	Yes
Intel® Fast Memory Access	Yes
Intel® Flex Memory Access	Yes

Intel® Data Protection Technology

Intel® AES New Instructions	No
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Intel® Platform Protection Technology

Trusted Execution Technology ‡	No
Execute Disable Bit ‡	Yes

Ordering and Compliance

All information provided is subject to change at any time, without notice. Intel may make changes to manufacturing life cycle, specifications, and product descriptions at any time, without notice. The information herein is provided "as-is" and Intel does not make any representations or warranties whatsoever regarding accuracy of the information, nor on the product features, availability, functionality, or compatibility of the products listed. Please contact system vendor for more information on specific products or systems.

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Refer to Datasheet for formal definitions of product properties and features.

“Announced” SKUs are not yet available. Please refer to the Launch Date for market availability.

Some products can support AES New Instructions with a Processor Configuration update, in particular, i7-2630QM/i7-2635QM, i7-2670QM/i7-2675QM, i5-2430M/i5-2435M, i5-2410M/i5-2415M. Please contact OEM for the BIOS that includes the latest Processor configuration update.

‡ This feature may not be available on all computing systems. Please check with the system vendor to determine if your system delivers this feature, or reference the system specifications (motherboard, processor, chipset, power supply, HDD, graphics controller, memory, BIOS, drivers, virtual machine monitor-VMM, platform software, and/or operating system) for feature compatibility. Functionality, performance, and other benefits of this feature may vary depending on system configuration.

“Conflict free” and “conflict-free” means “DRC conflict free”, which is defined by the U.S. Securities and Exchange Commission rules to mean products that do not contain conflict minerals (tin, tantalum, tungsten and/or gold) that directly or indirectly finance or benefit armed groups in the Democratic Republic of the Congo (DRC) or adjoining countries. Intel also uses the term "conflict-free" in a

broader sense to refer to suppliers, supply chains, smelters and refiners whose sources of conflict minerals do not finance conflict in the DRC or adjoining countries. Intel processors manufactured before January 1, 2013 are not confirmed conflict free. The conflict free designation refers only to product manufactured after that date. For Intel Boxed Processors, the conflict free designation refers to the processor only, not to any additional included accessories, such as heatsinks/coolers.

See <http://www.intel.com/content/www/us/en/architecture-and-technology/hyper-threading/hyper-threading-technology.html?wapkw=hyper+threading> for more information including details on which processors support Intel® HT Technology.

Max Turbo Frequency refers to the maximum single-core processor frequency that can be achieved with Intel® Turbo Boost Technology. See www.intel.com/technology/turboboost/ for more information.

The Recommended Customer Price ("RCP") is pricing guidance for Intel products. Prices are for direct Intel customers, typically represent 1,000-unit purchase quantities, and are subject to change without notice. Taxes and shipping, etc. not included. Prices may vary for other package types and shipment quantities, and special promotional arrangements may apply. If sold in bulk, price represents individual unit. Listing of these RCP does not constitute a formal pricing offer from Intel. Please work with your appropriate Intel representative to obtain a formal price quotation.

System and Maximum TDP is based on worst case scenarios. Actual TDP may be lower if not all I/Os for chipsets are used.

Low Halogen: Applies only to brominated and chlorinated flame retardants (BFRs/CFRs) and PVC in the final product. Intel components as well as purchased components on the finished assembly meet JS-709 requirements, and the PCB / substrate meet IEC 61249-2-21 requirements. The replacement of halogenated flame retardants and/or PVC may not be better for the environment.

For benchmarking data see <http://www.intel.com/performance>.

Intel processor numbers are not a measure of performance. Processor numbers differentiate features within each processor family, not across different processor families. See <http://www.intel.com/content/www/us/en/processors/processor-numbers.html> for details.

Processors that support 64-bit computing on Intel® architecture require an Intel 64 architecture-enabled BIOS.

